

1 Bill of materials

2 230604 RR

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5	Part	Value	Device	Package	Description
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7	C2	100nF	C0805	RC0805	Kondensator 0805
8	C3	100nF	C0805	RC0805	Kondensator 0805
9	C10	10uF	C1206	RC1206	Kondensator 1206
10	C11	10uF	C1206	RC1206	Kondensator 1206
11	C20	33pF	C0805	RC0805	Kondensator 0805
12	C21	not equipped	C0805	RC0805	Kondensator 0805
13	IC1	Mainboard	ST-DMATHHT2	DIL40-SPEZ	ST-DMA im 40-poligen Gehäuse
14	IC2	74HC05	74X05SMD	S014	Open Collector, invertierend 6mal
15	IC3	74HC74	74X74SMD	S014	D-Flip-Flop mit pos. Eingang 2mal
16	IC4	74HC10	74X10SMD	S014	NAND mit 3 Eingängen 3mal
17	R1	1K	R0805	RC0805	Widerstand 0805
18	R2	0R	R0805	RC0805	Widerstand 0805

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20 F-types can also be used instead of HC-Gates (IC2,IC3 and IC4).

21 The circuit was tested with HC-types.

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23 Please note!

24 All components are assembled on the bottom side of the board.

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26 Tip: Equip IC2, IC3 and IC4 first, then the capacitors and the resistor.

27 Finally, the individual solder cups (Lötkelche) follow, which are pressed
28 into the PCB from above and soldered from below. The solder cups can be
29 snapped out of an IC socket.